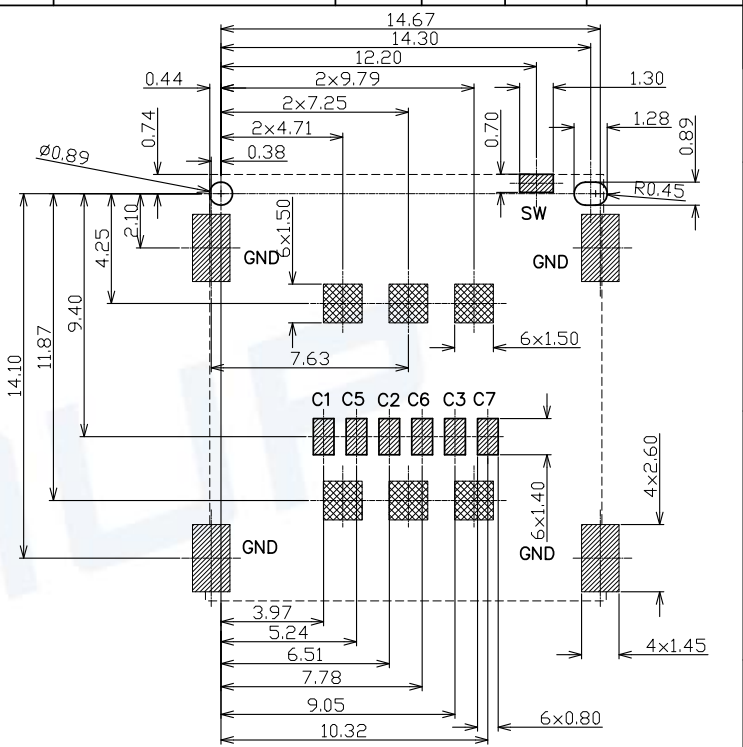
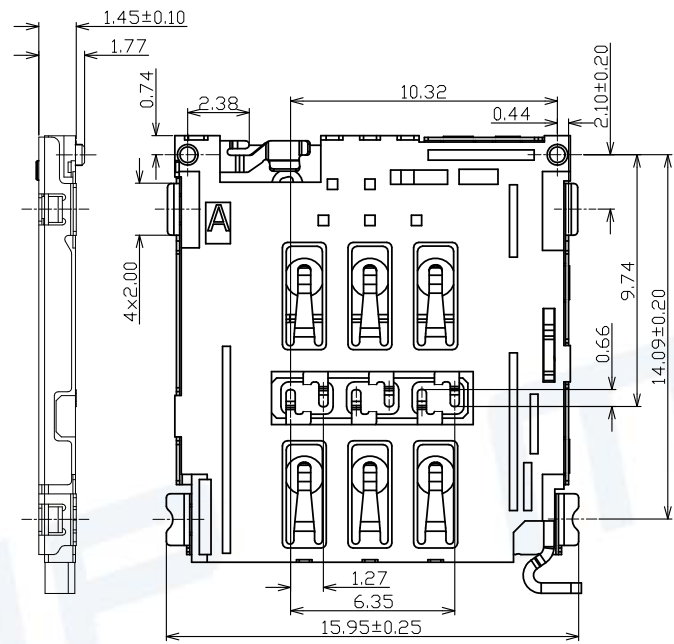
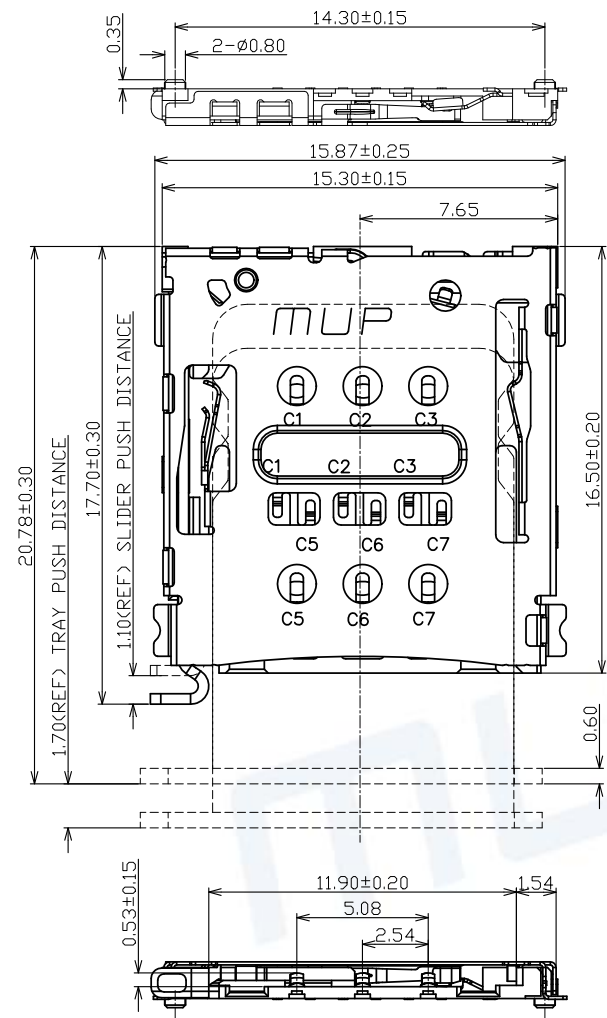


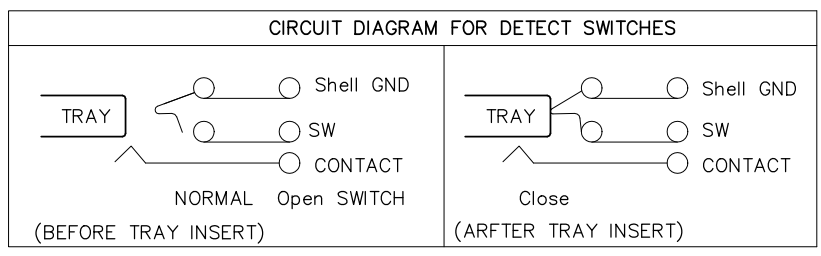
REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1	NEW REVISION				Henry Mar.12.2019
X2					



TECHNICAL CHARACTERISTICS
 1.General Characteristics
 Dimensions:16.50LX15.30WX1.55H mm
 TRAY MATING FORCE:1~10N
 TRAY UNMATING FORCE:1~10N
 Durability:1,500 cycles min.
 2.Electrical Characteristics
 Contact resistance:50mΩ typical, 100mΩMax
 Insulation resistance:>1000M/500V DC
 3.Solderability
 Vaporphase:215°C, 30sec.Max
 IR reflow:260°C,5sec.Max
 Manual soldering:370°C,3sec.Max
 4.Environmental Characteristics
 Operating temperature:-40°C~+85°C
 Operating humidity:10%~+95%RH

PAD AREA RECOMMENDED P.C.B LAYOUT COMPONENT SIDE(TOLERANCE ±0.05)
 CONNECTOR OUTLINE
 NO PATTERN AND VIA HOLE IN THIS AREA

NANO SIM CARD	
Pin No.	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
3	SWITCH	1	Copper Alloy	Contact area:Gold plated
4	SHELL	1	Stainless Steel	Solder area:Gold plated
5	Lever	1	Stainless Steel	
6	Cam	1	Stainless Steel	

Unless otherwise specified, other tolerance are:

MUP MUP INDUSTRIAL CO.,LTD.

X ±0.35	X* ±5°	NAME: SINGLE NANO-SIM Card Connector
X.X ±0.25	X.X* ±4°	MODEL NO: MUP-C7804-1
X.XX ±0.15	X.XX* ±3°	TYPE: H1.45mm Normally Open With Card Tray type
X.XXX ±0.10	X.XXX* ±2°	
PROJ.	UNIT mm	SCALE 1:1
DRAWN Henry Mar.12.2019		DWG NO.: DWG-MUP-C7804-1
CHECKED Henry Mar.12.2019		SHEET 1/1
APPROVAL Simon Mar.12.2019		REVISION X1

